

Electronic Patent Application Fee Transmittal				
Application Number:		10541586		
Filing Date:		30-Sep-2005		
Title of Invention:		CURING RESIN COMPOSITION, ADHESIVE EPOXY RESIN PASTE, ADHESIVE EPOXY RESIN SHEET, CONDUCTIVE CONNECTION PASTE, CONDUCTIVE CONNECTION SHEET, AND ELECTRONIC COMPONENT JOINED BODY		
First Named Inventor/Applicant Name:		Koji Watanabe		
Filer:		Burton A. Amernick/Pam Rollins-Butler		
Attorney Docket Number:		21581-00456-US		
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1810